Preferred Device

Advance Information

Power MOSFET 8 Amps, 500 Volts

N-Channel TO-220 and D2PAK

Designed for high voltage, high speed switching applications in power supplies, converters, power motor controls and bridge circuits.

Features

- Higher Current Rating
- Lower R_{DS(on)}
- Lower Capacitances
- Lower Total Gate Charge
- Tighter V_{SD} Specifications
- Avalanche Energy Specified

Typical Applications

- Switch Mode Power Supplies
- PWM Motor Controls
- Converters
- Bridge Circuits

MAXIMUM RATINGS ($T_C = 25^{\circ}C$ unless otherwise noted)

Rating	Symbol	Value	Unit
Drain-Source Voltage	V _{DSS}	500	Vdc
Drain–Gate Voltage (R _{GS} = 1.0 M Ω)	V _{DGR}	500	Vdc
Gate–Source Voltage - Continuous - Non–Repetitive (t _p ≤10 ms)	V _{GS} V _{GSM}	±20 ±40	Vdc
Drain - Continuous - Continuous @ 100°C - Single Pulse (t _p ≤ 10 μs)	I _D	8.0 6.2 28	Adc
Total Power Dissipation Derate above 25°C	PD	202 1.61	Watts W/°C
Operating and Storage Temperature Range	T _J , T _{stg}	-55 to 150	°C
Single Drain–to–Source Avalanche Energy – Starting $T_J = 25^{\circ}C$ ($V_{DD} = 100 \text{ Vdc}, V_{GS} = 10 \text{ Vdc},$ $I_L = 8 \text{ A}, L = 10 \text{ mH}, R_G = 25 \Omega$)	E _{AS}	320	mJ
Thermal Resistance – Junction–to–Case – Junction–to–Ambient – Junction–to–Ambient (Note 1.)	R _θ JC R _θ JA R _θ JA	0.62 62.5 50	°C/W
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds	TL	260	°C

When surface mounted to an FR4 board using the minimum recommended pad size.

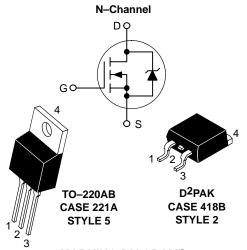
This document contains information on a new product. Specifications and information herein are subject to change without notice.



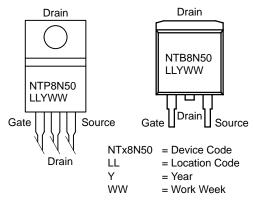
ON Semiconductor™

http://onsemi.com

8 AMPERES 500 VOLTS RDS(on) = 750 m Ω



MARKING DIAGRAMS AND PIN ASSIGNMENTS



ORDERING INFORMATION

Device	Package	Shipping
NTP8N50	TO-220AB	50 Units/Rail
NTB8N50	D ² PAK	50 Units/Rail
NTB8N50T4	D ² PAK	800/Tape & Reel

Preferred devices are recommended choices for future use and best overall value.

ELECTRICAL CHARACTERISTICS ($T_C = 25^{\circ}C$ unless otherwise noted)

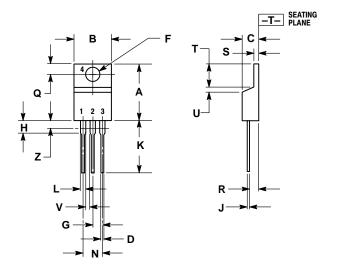
CI	Symbol	Min	Тур	Max	Unit	
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage (VGS = 0 Vdc, ID = 0.25 mAdc)		V(BR)DSS	500	_	_	Vdc
Temperature Coefficient (Pos	,		_	560	-	mV/°C
Zero Gate Voltage Collector Current (VDS = 500 Vdc, VGS = 0 Vdc) (VDS = 500 Vdc, VGS = 0 Vdc, TJ =125°C)		IDSS	_ _	_ _	10 100	μAdc
Gate-Body Leakage Current (V	$V_{GS} = \pm 20 \text{ Vdc}, V_{DS} = 0)$	IGSS(f) IGSS(r)	_ _	_ _	100 100	nAdc
ON CHARACTERISTICS (Note 2	2.)		•	•		•
Gate Threshold Voltage		VGS(th)				Vdc
I _D = 0.25 mA, V _{DS} = V _{GS} Temperature Coefficient (Neg	gative)		2.0 –	2.6 6.5	4.0 -	mV/°C
Static Drain-to-Source On-Res	sistance ($V_{GS} = 10 \text{ Vdc}$, $I_D = 4.0 \text{ Adc}$)	R _{DS(on)}	_	600	750	mOhm
$ \begin{aligned} & \text{Drain-to-Source On-Voltage} \\ & (\text{VGS} = 10 \text{ Vdc}, \text{I}_D = 8.0 \text{ Adc} \\ & (\text{VGS} = 10 \text{ Vdc}, \text{I}_D = 4.0 \text{ Adc} \end{aligned} $	V _{DS(on)}	_ _	_ _	7.2 6.3	Vdc	
Forward Transconductance (V	os = 15 Vdc, I _D = 4.0 Adc)	9FS	4.0	7.0	_	Mhos
DYNAMIC CHARACTERISTICS						
Input Capacitance		C _{iss}	_	1530	2140	pF
Output Capacitance	(V _{DS} = 25 Vdc, V _{GS} = 0 Vdc, f = 1.0 MHz)	C _{oss}	-	380	530	
Transfer Capacitance	1 = 1.0 m 12)	C _{rss}	-	15	30	
SWITCHING CHARACTERISTIC	S (Note 3.)		•	•	•	
Turn-On Delay Time		td(on)	_	14	30	ns
Rise Time	$(V_{DD} = 250 \text{ Vdc}, I_D = 12 \text{ Adc},$	t _r	-	17	30	
Turn-Off Delay Time	$V_{GS} = 10 \text{ Vdc},$ $R_{G} = 9.1 \Omega)$	td(off)	-	34	70	
Fall Time		t _f	-	25	50	
Gate Charge	$(V_{DS} = 400 \text{ Vdc}, I_{D} = 8.0 \text{ Adc}, V_{GS} = 10 \text{ Vdc})$	QT	-	25	40	nC
		Q ₁	_	6.0	_	
		Q ₂	_	8.0	-	
		Q ₃	_	12	_	
SOURCE-DRAIN DIODE CHAR	ACTERISTICS			1		1
Forward On-Voltage (Note 2.)		V _{SD}				Vdc
	$(I_S = 8.0 \text{ Adc}, V_{GS} = 0 \text{ Vdc})$ $(I_S = 8.0 \text{ Adc}, V_{GS} = 0 \text{ Vdc}, T_J = 125^{\circ}\text{C})$		_	0.9 0.8	1.1 -	
Reverse Recovery Time		t _{rr}	_	375	_	ns
	# 00AL W 0W	ta	-	155	-	1
	$(I_S = 8.0 \text{ Adc}, V_{GS} = 0 \text{ Vdc},$ $dI_S/dt = 100 \text{ A/}\mu\text{s})$	t _b	-	220	_	
Reverse Recovery Stored Charge		Q _{RR}		2.75	_	μС
NTERNAL PACKAGE INDUCTA	ANCE			•		
Internal Drain Inductance		L _D				nΗ
(Measured from contact screet) (Measured from the drain lea		_ _	3.5 4.5	_ _		
Internal Source Inductance (Measured from the source le	LS	_	7.5	_		
					•	•

Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.
 Switching characteristics are independent of operating junction temperature.

PACKAGE DIMENSIONS

TO-220 THREE-LEAD TO-220AB

CASE 221A-09 **ISSUE AA**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

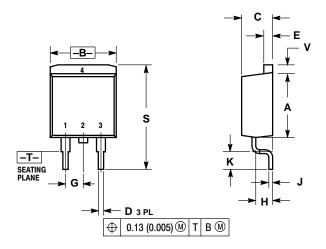
	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.405	9.66	10.28
C	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.42	2.66
Н	0.110	0.155	2.80	3.93
J	0.018	0.025	0.46	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
٧	0.045		1.15	
Z		0.080		2.04

STYLE 5: PIN 1.

GATE

- DRAIN SOURCE DRAIN 3.

D²PAK CASE 418B-03 ISSUE D



NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIN	LLIMETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.340	0.380	8.64	9.65	
В	0.380	0.405	9.65	10.29	
C	0.160	0.190	4.06	4.83	
D	0.020	0.035	0.51	0.89	
Е	0.045	0.055	1.14	1.40	
G	0.100 BSC		2.54 BSC		
Н	0.080	0.110	2.03	2.79	
J	0.018	0.025	0.46	0.64	
K	0.090	0.110	2.29	2.79	
S	0.575	0.625	14.60	15.88	
٧	0.045	0.055	1.14	1.40	

STYLE 2: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN

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